24th IEEE European Test Symposium
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http://www.ieee-ets.org

ETS 19

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Call for Papers

The IEEE European Test Symposium (ETS) is Europe's premier forum dedicated to presenting and discussing scientific results, emerging ideas, applications, hot topics and new trends in the area of electronic-based circuits and system testing, reliability, security and validation. In 2019, ETS will take place in the Congress Center in Baden-Baden. It is organized by the Karlsruhe Institute of Technology (KIT), which co-sponsors the event jointly with the IEEE Council on Electronic Design Automation (CEDA). In addition to scientific paper submissions, this year ETS also offers an embedded workshop track dedicated to work in progress and case studies as well as a PhD forum. The special track on Emerging Test Strategies (ETS²) will again focus on upcoming problems and ideas in an industrial context. A Test Spring School will be organized in conjunction with ETS'19.

You are invited to participate and submit your contributions to ETS'19. The areas of interest include (but are not limited to) the following topics:

- *Analog, Mixed-signal and RF Test*
- *ATE Hardware and Software*
- *Automatic Test Generation*
- *Board Test and Diagnosis*
- *Boundary Scan Test*
- *Built-In Self-Test (BIST)*
- *Current-Based Test*
- *Defect-Based Test*
- *Delay and Performance Test*
- *Dependability and Functional Safety*
- *Design for Test (DFT)*
- *Design for Manufacturing (DFM)*
- *Design Verification and Validation*
- *Diagnosis and Silicon Debug*
- *Economics of Test*
- *Failure Analysis*
- *Fault Modeling and Simulation*

- *Fault Tolerance*
- *Hardware Trojans*
- *Hardware Security*
- *High-Speed I/0 Test*
- *GPU Test*
- *Low-Power IC Test*
- *Memory Test and Repair*
- *MEMS Test*
- *Microprocessor Test*
- *Multi-/Many-core Processor Test*
- *Nanotechnology Test*
- *On-line Test*
- *Power Issues in Test*
- *Design for Reliability*
- *Reliability-Security Trade-offs*

- *Security Issues in Test*
- *Self-Repair*
- *Signal Integrity Test*
- *Stacked or 3D ICs Test*
- *Standards in Test*
- *System Test*
- *SiP and SoC Test*
- *Test Synthesis*
- *Test, Reliability and Security of Emerging Technologies and Architectures*
- *Test of Reconfigurable Systems*
- *Test Quality*
- *Thermal Issues in Test*
- *Transient and Soft Errors*
- *Variability Issues in Test*
- *Yield Analysis and Enhancement*

Publications – ETS'19 will produce Formal Proceedings of scientific papers as well as an Informal Digest of papers including additional material. The Best Paper Award of ETS'19 will be presented at ETS'20.

Submissions – ETS'19 seeks original, unpublished contributions of the following types:
- **Scientific papers** for the Formal Proceedings, presenting novel and complete research work.
- **Extended Abstracts for Embedded Workshop papers** including 'work in progress' and 'case studies'.
- **Contributions for the PhD forum** (deadline in March 2019).
- **Contributions for ETS²**.
- **Proposals for panels, embedded tutorials**, and other **special sessions**.
- **Vendor presentations** focusing on new features of test related products.

Detailed submission information and guidelines are posted on the ETS'19 web page.

The ETS'19 organizing committee strongly encourages the organization of fringe meetings and workshops. Details can be found on the ETS'19 web page.

Key Dates:
- Submission deadline: **December 11, 2018**
- Notification of acceptance: **February 15, 2019**
- Camera-ready manuscript: **March 22, 2019**

Further Information:

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